


## Standardized Information for Process/Product Change Notification (PCN)

1. PCN basic data		
1.1 Company	 TAIWAN SEMICONDUCTOR	Taiwan Semiconductor Co., Ltd. 11 Fl., No. 205, Sec. 3, Beishin Rd., Xindian Dist., New Taipei City, 231 Taiwan R.O.C.
1.2 PCN No.	PCN16018-1	
1.3 Title of PCN	Add second assembly source	
1.4 Product Category	Active Components - Discrete Components	
1.5 Issue date	2016/07/06	
1.6 PCN revision history (optional)	1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)

Form provided by ZVEI - Revision 2.0.6

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	Sunnie Pan	
2.1.2 Phone	+886-2-8913-1588 Ext:2205	
2.1.3 Email	sunnie@mail.ts.com.tw	
2.2 Team supplier (optional)		
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)
Karen Wu	+886-2-8913-1588 Ext:2123	karen_wu@mail.ts.com.tw
Ken	+886-2-8913-1588 Ext:2103	ken_kan@mail.ts.com.tw
Venkey	+86-543-869-1091 Ext:3101	venkey@mail.tsview.com.cn

3. Changes			
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PA-11	PROCESS - ASSEMBLY	Change of mold compound
#2	SEM-PA-18	PROCESS - ASSEMBLY	Move of all or part of assembly to a different location/site/subcontractor.
#3			
#4			
#5			

4. Description of change		
	Old	New
Change #1	Packing code: E2,E2G,E3,E3G	Packing code: E2,E2G,E3,E3G, F2,F2G,F3,F3G,F4,F4G
Change #2	Assembly and test site in Taiwan	Assembly and test site in Taiwan Exapnd one more assembly and test site in China
Change #3	molding compound: A Type	molding compound: A Type and B Type
Change #4		
Change #5		
4.6 Anticipated impact on form, fit, function, reliability or processability?	NA	
4.7 Reference parts with customer number (optional)		

5. Reason / motivation for change	
5.1 Motivation	Expand production capacity
5.2 Additional explanation (optional)	

6. Marking of parts / traceability of change	
6.1 Description	

[illegible]